















ESD

TVS

MOS

LDO

Diode

Sensor

DC-DC

Product Specification

Domestic Part Number	SS32B - SS320B
Overseas Part Number	SS32B - SS320B
▶ Equivalent Part Number	SS32B - SS320B





Schottky Diodes

■ Features

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications



■ Absolute Maximum Ratings and Electrical Characteristics

Ratings at 25° C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	Symbols	SS32B	SS34B	SS36B	SS38B	SS310B	SS312B	SS315B	SS320B	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	20	40	60	80	100	120	150	200	V
Maximum RMS voltage	V _{RMS}	14	28	42	56	70	84	105	140	V
Maximum DC Blocking Voltage	V _{DC}	20	40	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current	I _{F(AV)}	3.0								Α
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	80								А
Max Instantaneous Forward Voltage at 3 A	V _F	0.55		0.	70 0.85		0.95		V	
Maximum DC Reverse Current $T_a = 25^{\circ}$ C at Rated DC Reverse Voltage $T_a = 100^{\circ}$ C	I _R	0.5 5 0.3 3							mA	
Typical Junction Capacitance (1)	Cj	450 400						pF		
Typical Thermal Resistance (2)	$R_{\theta JA}$	60								°C/W
Operating Junction Temperature Range	Tj	-55 ~ + 150								°C
Storage Temperature Range	T_{stg}	-55 ~ +150							°C	

^{* 1} Measured at 1MHz and applied reverse voltage of 4V D.C

^{* 2} P.C.B. mounted with $~2^{\prime\prime}~\times 2^{\prime\prime}~$ (5×5 cm) copper pad areas.



■ Typical Characterisitics

Fig.1 Forward Current Derating Curve

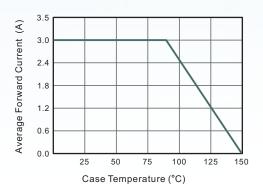


Fig.3 Typical Forward Characteristic

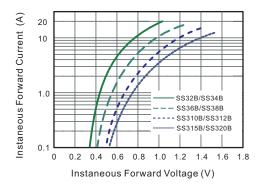


Fig.5 Maximum Non-Repetitive Peak

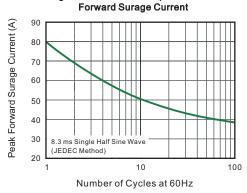


Fig.2 Typical Reverse Characteristics

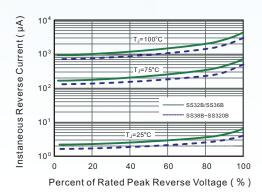


Fig.4 Typical Junction Capacitance

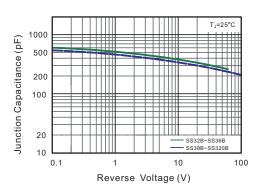
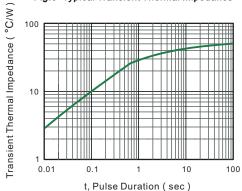
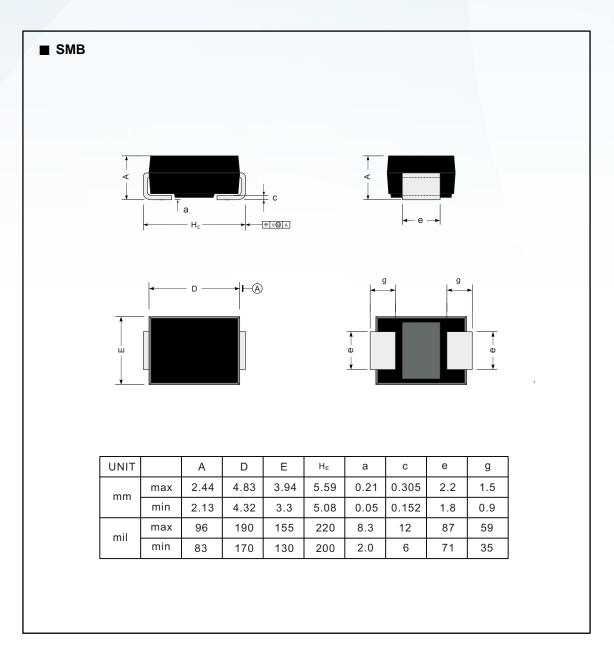


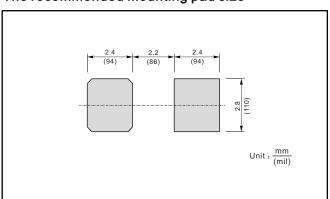
Fig.6- Typical Transient Thermal Impedance







The recommended mounting pad size





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